TE Internal #: 5645518-1
5.23 mm [.206 in] Socket Length, 1.91 mm [.075 in] PCB Hole,
Closed Bottom, .653 – .823 mm² Wire, 19 – 18 AWG, Cable-to-Board, Pin Sockets

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Connectors > Socket Connectors > Pin Sockets > Miniature Spring Sockets: Closed Bottom, Beryllium Copper, 6.5A











Socket Length: 5.23 mm [.206 in]

PCB Hole Diameter: 1.91 mm [.075 in]
Socket Sleeve Style: Closed Bottom

Wire Size: **19 – 18 AWG**

All Miniature Spring Sockets: Closed Bottom, Beryllium Copper, 6.5A (10)

Features

Product Type Features

Connector & Contact Terminates To	Printed Circuit Board
Socket Sleeve Style	Closed Bottom
Connector System	Cable-to-Board
Sealable	No

Configuration Features

Body Features

Sleeve Plating Material	Tin
Sleeve Material	Copper

Contact Features

Contact Spring Plating Material	Gold
Contact Base Material	Beryllium Copper
Contact Mating Area Plating Material Thickness	30 μm[30 μin]
	30 μin



Contact Current Rating (Max)	6.5 A
Termination Features	
Termination Method to PCB	Through Hole - Press-Fit
Termination Method to Wire & Cable	Solder
Insertion Method	Hand/Semi-Automatic/Automatic
Dimensions	
PCB Thickness (Recommended)	.79 – 3.18 mm[.031 – .125 in]
Socket Length	5.23 mm[.206 in]
PCB Hole Diameter	1.91 mm[.075 in]
Wire Size	19 – 18 AWG
Mating Pin Diameter Range	.96 – 1.07 mm[.038 – .042 in]
Usage Conditions	
Operating Temperature Range	-65 – 125 °C[-85 – 257 °F]
Operation/Application	
Circuit Application	Power & Signal
Packaging Features	
Packaging Method	Reel
Packaging Quantity	50000
Other	
Spring Material	Beryllium Copper

Product Compliance

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JAN 2025 (247) Candidate List Declared Against: JAN 2025 (247) Does not contain REACH SVHC
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free



Solder Process Capability

Pin-in-Paste capable to 260°C

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Customers Also Bought



















Documents

Product Drawings
MSS SER 4 SPL ON STRIP

English



CAD Files

Customer View Model

ENG_CVM_5645518-1_O1.3d_igs.zip

English

Customer View Model

ENG_CVM_5645518-1_O1.3d_stp.zip

English

Customer View Model

ENG_CVM_5645518-1_O1.2d_dxf.zip

English

3D PDF

English

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Product Specifications

Product Specification

English